

**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:** Sandhu, et al.

**Serial No.:** 09/012,685

**Filed:** January 23, 1998

**For:** LOW-RESISTANCE CONTACT TO  
SILICON HAVING A TITANIUM  
SILICIDE INTERFACE, AN  
AMORPHOUS TITANIUM  
NITRIDE BARRIER LAYER AND A  
CONDUCTIVE PLUG

**Via Hand Delivery**

**Examiner:** Nadasz

**Group Art Unit:** 1762

**Attorney Docket No.:** 3264.1US (92-280.04)

**POWER OF ATTORNEY, REVOCATION OF PRIOR**  
**POWER OF ATTORNEY (37 C.F.R. § 1.36) and REQUEST TO**  
**CHANGE CORRESPONDENCE ADDRESS (37 C.F.R. § 1.33(d))**  
**with STATEMENT PURSUANT TO 37 C.F.R. § 3.73**

Assistant Commissioner for Patents  
Washington, D.C. 20231

Sir:

As assignee of the entire interest in the above-identified application, all powers of attorney previously given herein are HEREBY REVOKED and the following attorneys are hereby appointed to prosecute and transact all business in the U.S. Patent and Trademark Office in connection herewith.

David V. Trask, Reg. No. 22,012  
William S. Britt, Reg. No. 20,969  
Thomas J. Rossa, Reg. No. 26,799  
Laurence B. Bond, Reg. No. 30,549  
Joseph A. Walkowski, Reg. No. 28,765  
James R. Duzan, Reg. No. 28,393

Allen C. Turner, Reg. No. 33,041  
Kent S. Burningham, Reg. No. 30,453  
Edgar R. Cataxinos, Reg. No. 39,931  
Brick G. P wer, Reg. No. 38,581  
Kenneth C. Booth, Reg. No. 42,342  
Samuel E. Webb, Reg. No. P-44,394  
Michael L. Lynch, Reg. No. 30,871  
Lia M. Pappas, Reg. No. 34,095

In accordance with 37 C.F.R. § 1.33(d), please change the address for all purposes in connection with the above-identified patent and direct all communications to:

JAMES R. DUZAN  
TRASK, BRITT & ROSSA  
P. O. Box 2550  
Salt Lake City, Utah 84110  
(801) 532-1922

Pursuant to 37 C.F.R. § 3.73, the undersigned representative of the Assignee has reviewed the evidentiary documents, specifically the Assignment to Micron Technology, Inc. recorded on February 6, 1997 at Reel 8389, Frame 0293, and certifies that to the best of his knowledge and belief, title remains in the name of Micron Technology, Inc. as Assignee of record of the entire interest in the above-identified patent application.

The undersigned further avers that he is empowered to make and sign the foregoing certification on behalf of the Assignee, and to take the action set forth herein on behalf of the Assignee, pursuant to a resolution of its Board of Directors.

Respectfully submitted,

MICRON TECHNOLOGY, INC.

Dated: 2/22/1999

By: MLL  
Michael L. Lynch, Esq.  
Reg. No. 30,871  
Chief Patent Counsel, an authorized  
representative empowered to grant the  
foregoing power of attorney

## DECLARATION AND POWER OF ATTORNEY

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled LOW-RESISTANCE CONTACT TO SILICON HAVING A TITANIUM SILICIDE INTERFACE, AN AMORPHOUS TITANIUM NITRIDE BARRIER LAYER AND A REFRactory METAL PLUG, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims.

I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, Section 1.56.

I hereby claim the benefit of any earlier filing date in the United States to which I am entitled under Title 35 of the United States Code, §120 and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35 of the United States Code, Section 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37 of the Code of Federal Regulations, Section 1.56 which became available between the filing date of the prior application and the national or PCT international filing date of this application.

I hereby appoint the following attorney(s) and/or agent(s) to prosecute this application and to transact all business in the Patent and Trademark Office connected therewith:

William R. Bachand	Registration No. 34,980
Susan B. Collier	Registration No. 34,566
Angus C. Fox, III	Registration No. 31,828
Kevin D. Martin	Registration No. 37,882
Lia M. Pappas	Registration No. 34,095
David J. Paul	Registration No. 34,692

Send correspondence to: Angus C. Fox, III, Patent Attorney  
Micron Semiconductor, Inc.  
2805 E. Columbia Rd.  
Boise, Idaho 83706

Direct telephone calls to: Angus C. Fox, III  
(208) 368-4509

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18 of the United States Code, Section 1001 and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of sole or first inventor: Gurtej S. Sandhu

Inventor's Signature: Gurt Sma Sandhu Date: 8/2/94  
(First, Middle Initial, Last)

Residence  
City, State, Country: Boise, Idaho, United States of America

Citizenship: British

Post Office Address: 2566 Waterbury Lane  
Boise, Idaho 83706

Full name of second joint inventor: Trung T. Doan

Inventor's Signature: Trung T. Doan Date: 8/7/94  
(First, Middle Initial, Last)

Residence  
City, State, Country: Boise, Idaho, United States of America

Citizenship: United States of America

Post Office Address: 1574 Shenandoah Drive  
Boise, Idaho 83712

Full name of third joint inventor: Tyler A. Lowrey

Inventor's Signature: John A. Lowry Date: 8/9/97  
(First, Middle Initial, Last)

Residence  
City, State, Country: Boise, Idaho, United States of America

Citizenship: United States of America

Post Office Address: 2599 E. Plateau  
Boise, Idaho 83712